

TEST ASSEMBLY FOR INTEGRATED CIRCUIT PACKAGE

Abstract

A test assembly for an integrated circuit package includes a package substrate and a test board. The package substrate is provided with a plurality of first contact pads linked in a first daisy chain pattern. The test board has a plurality of second contact pads linked in a second daisy chain pattern and a plurality of test pads. All of the second contact pads are divided into a plurality of groups each connected to one pair of test pads. All of the second contact pads in any group are arranged in a line. The present invention further provides a method of testing an integrated circuit package utilizing the aforementioned package substrate and test board.